

ABSTRACT OF THE DISCLOSURE

Even when the substrate size increases, the substrate is processed (etched) uniformly. An ultrasonic oscillator (103) is arranged under an etching container (101). A substrate (120) is horizontally arranged in the etching container (101). Accordingly, the substrate (120) is arranged while making a surface face the ultrasonic oscillator (103). The substrate (120) is etched while being rotated by a rotating mechanism (130).